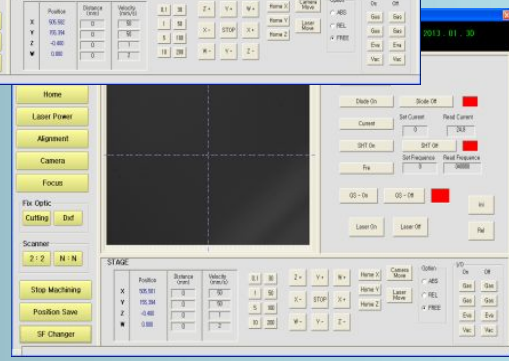
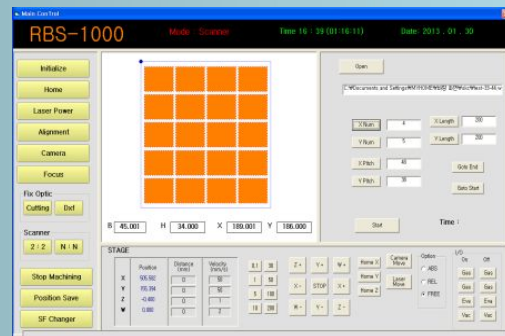
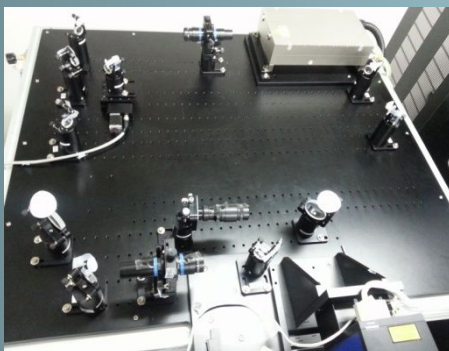
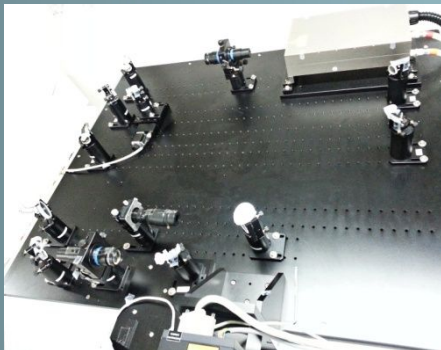
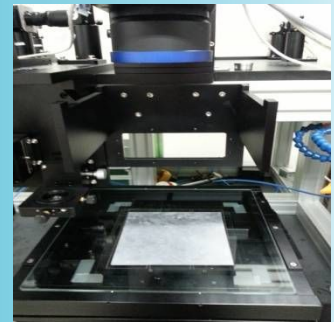
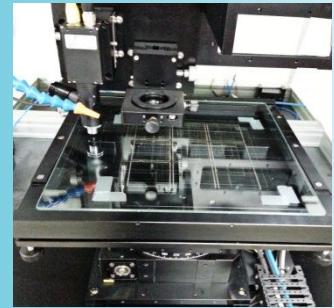
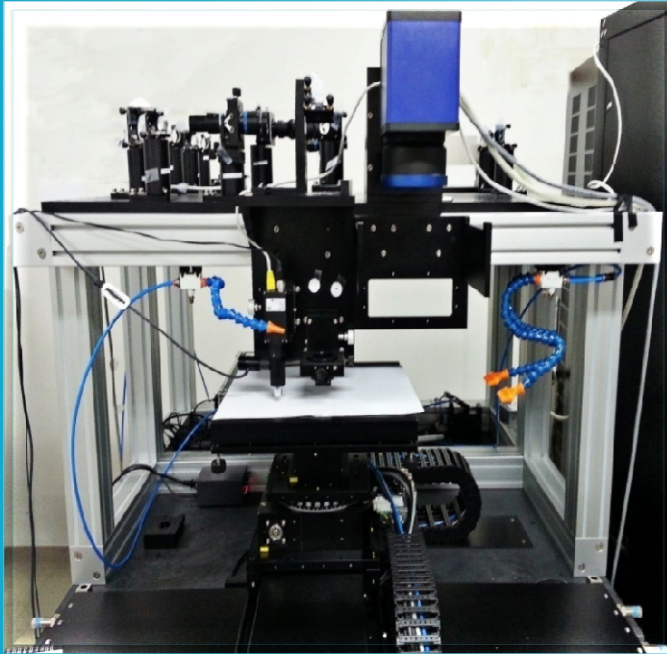


Hole Drilling Machine (UV Laser System)

KOS-SF1000RBS



Applications

- ❖ Hole Drilling System On Printed wiring board
- ❖ Silicon Wafer Cutting
- ❖ Scribing for Sapphire Wafer
- ❖ Film Cutting/Scribing

Beam wavelength	355nm (UV)
Average power	20W at 40kHz
Max. Area(mm)	560 x 650 x 1panel
XY축 이송속도(mm/min)	50,000
Frequency(kHz)	30-150
Scan Area(mm)	50 X50
Spot size(μm)	Scanner type: <10
Drilling speed	> 932 hole/sec (single layer thru hole)
Scanning speed	2000pps
Hole positioning accuracy(μm)	< ±5

* Including both table & galvano positioning